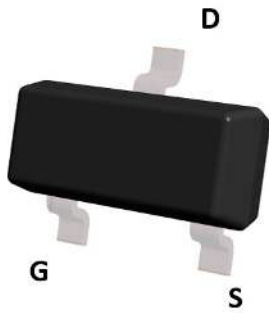
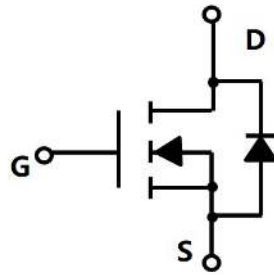
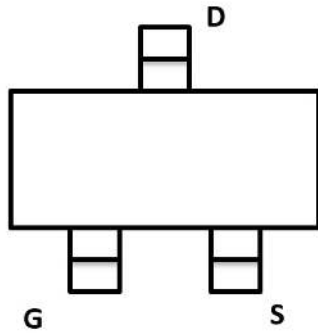


N-Channel Enhancement Mode Field Effect Transistor



Top View

SOT-23



Product Summary

- V_{DS} 60V
- I_D 3.0A
- $R_{DS(ON)}$ (at $V_{GS}= 10V$) < 100mohm
- $R_{DS(ON)}$ (at $V_{GS}= 4.5V$) < 120mohm
- $R_{DS(ON)}$ (at $V_{GS}= 2.5V$) < 200mohm

General Description

- Trench Power LV MOSFET technology
- High Density Cell Design for Low $R_{DS(ON)}$
- High Speed switching

Applications

- Battery protection
- Load switch
- Power management

■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	V_{DS}	60	V
Gate-source Voltage	V_{GS}	± 16	V
Drain Current	I_D	$T_A=25^\circ\text{C}$	3
		$T_A=70^\circ\text{C}$	2.4
Pulsed Drain Current ^A	I_{DM}	12	A
Total Power Dissipation @ $T_A=25^\circ\text{C}$ Steady State	P_D	1.2	W
Thermal Resistance Junction-to-Ambient ^B	$R_{\theta JA}$	105	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	$^\circ\text{C}$

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJL03N06B	F2	S10B.	3000	30000	120000	7" reel



YJL03N06B

■ Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60V, V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±16V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	0.65	0.95	1.55	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 3A		86	100	mΩ
		V _{GS} = 4.5V, I _D = 2A		90	120	
		V _{GS} = 2.5V, I _D = 1A		100	200	
Diode Forward Voltage	V _{SD}	I _S = 3.0A, V _{GS} =0V		0.8	1.2	V
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =30V, V _{GS} =0V, f=1MHZ		451		pF
Output Capacitance	C _{oss}			38		
Reverse Transfer Capacitance	C _{rss}			31		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} = 10V, V _{DS} = 30V, I _D = 3.0A		13.8		nC
Gate-Source Charge	Q _{gs}			2.2		
Gate-Drain Charge	Q _{gd}			1.9		
Reverse Recovery Charge	Q _{rr}	I _F = 3A, di/dt=100A/us		7.6		ns
Reverse Recovery Time	t _{rr}			30		
Turn-on Delay Time	t _{D(on)}	V _{GS} = 10V, V _{DS} = 30V, I _D = 1.5A R _{GEN} = 3Ω		3		ns
Turn-on Rise Time	t _r			18		
Turn-off Delay Time	t _{D(off)}			17		
Turn-off fall Time	t _f			22		

A. Pulse Test: Pulse Width ≤ 300us, Duty cycle ≤ 2%.

B. R_{θJA} is the sum of the junction-to-lead and lead-to-ambient thermal resistance, where the lead thermal reference is defined as the solder mounting surface of the drain pins. R_{θJL} is guaranteed by design, while R_{θJA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.



■ Typical Performance Characteristics

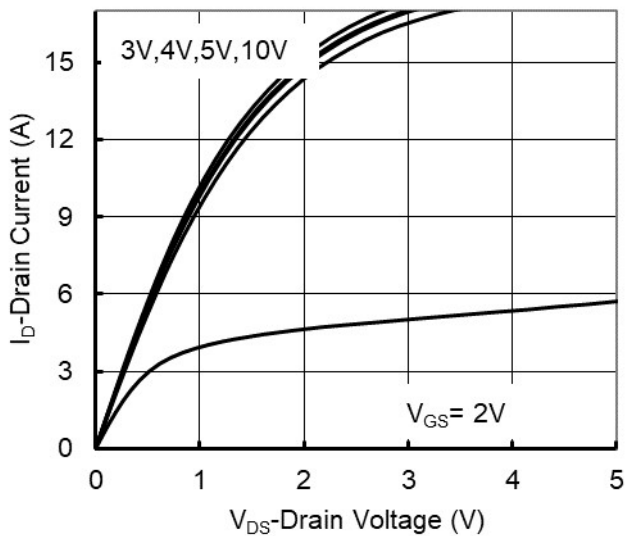


Figure1. Output Characteristics

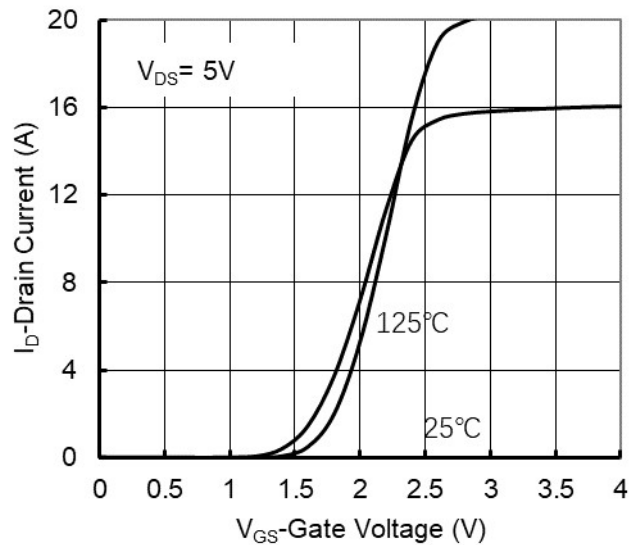


Figure2. Transfer Characteristics

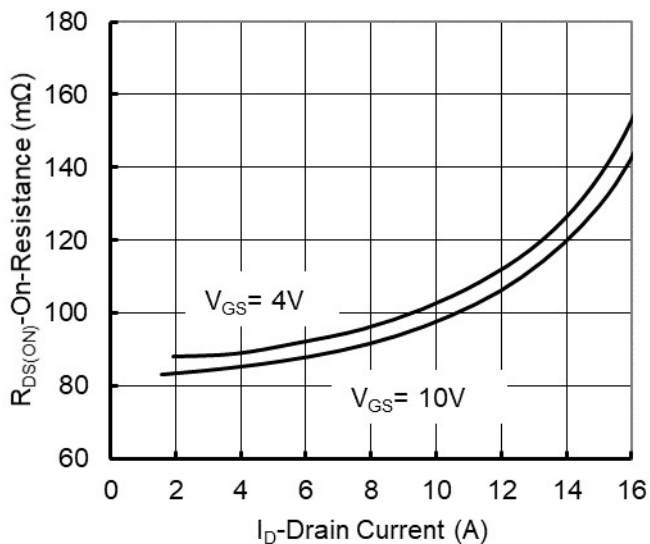


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

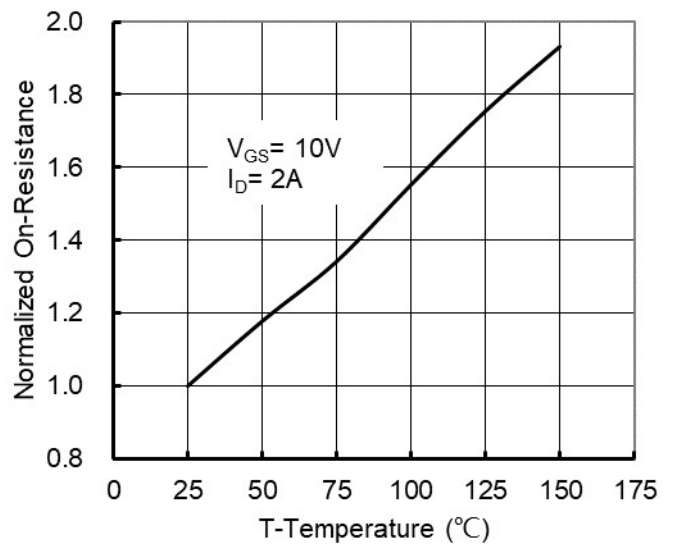


Figure 4: On-Resistance vs. Junction Temperature

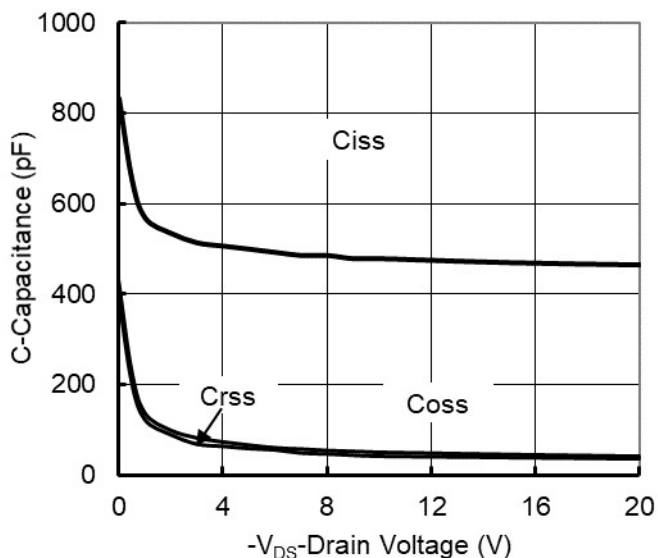


Figure5. Capacitance Characteristics

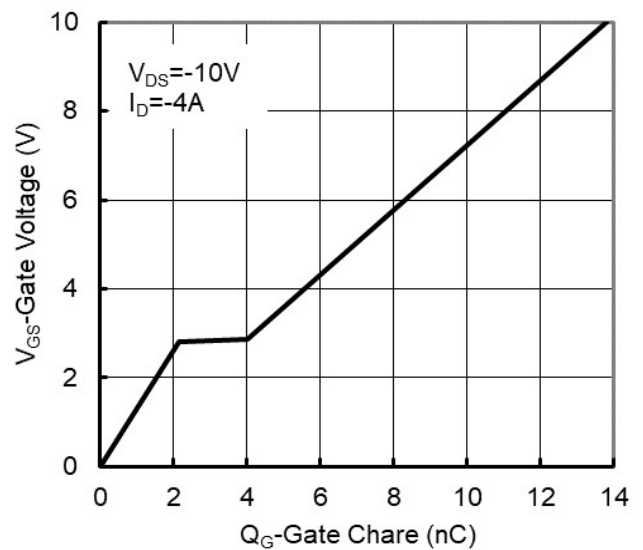


Figure6. Gate Charge



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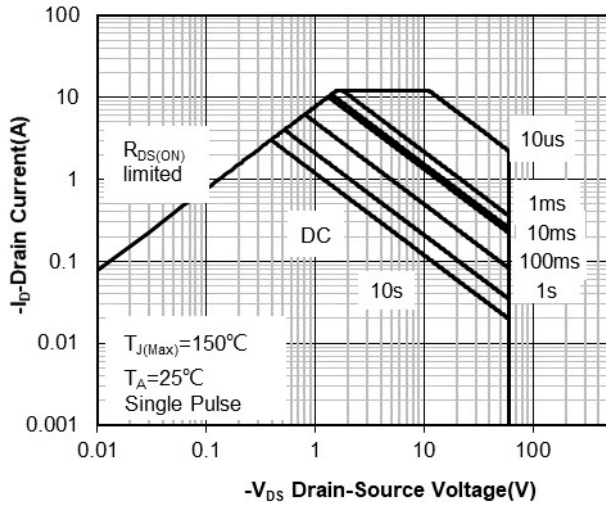


Figure7. Safe Operation Area

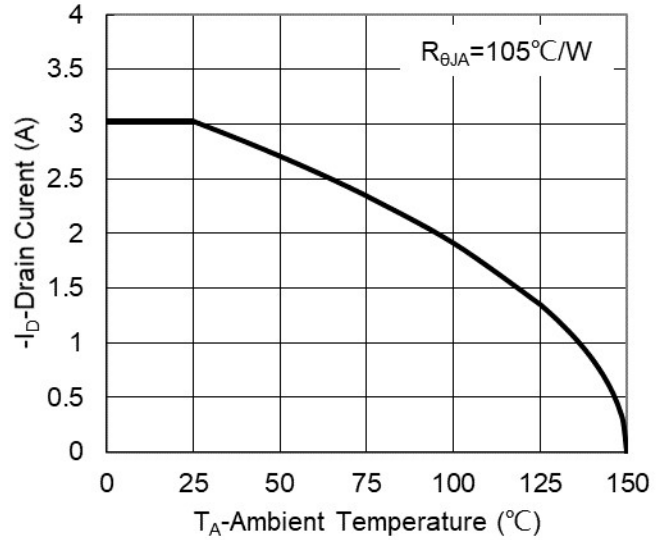


Figure8. Maximum Continuous Drain Current vs Ambient Temperature

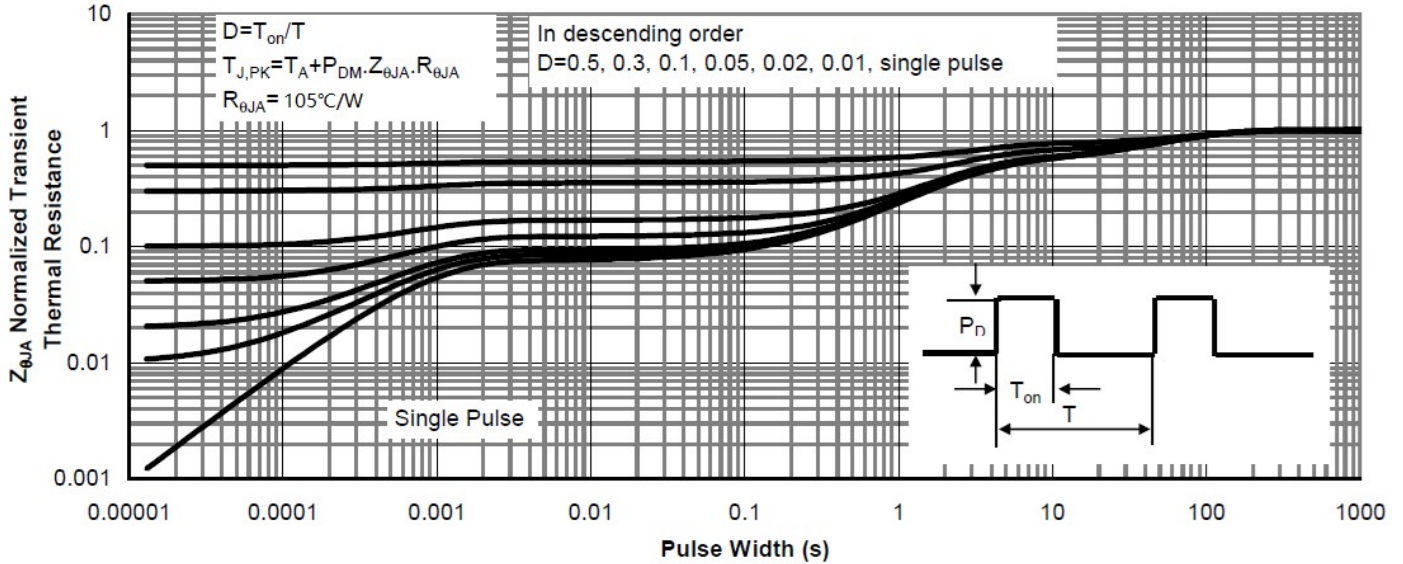
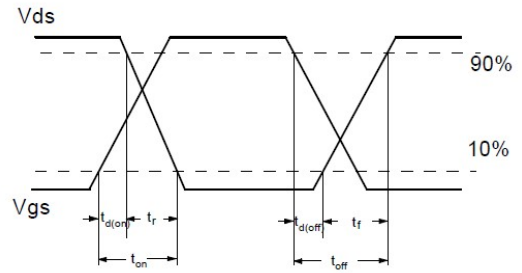
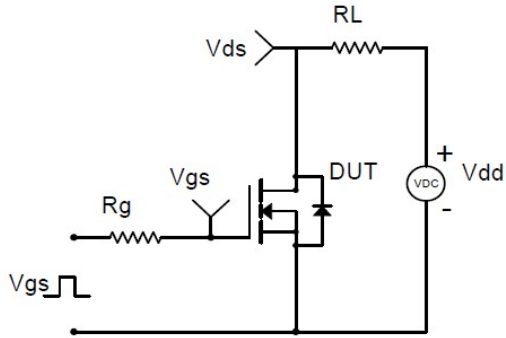
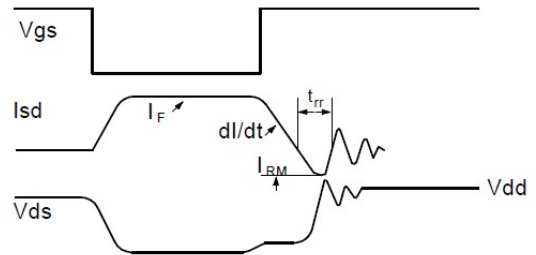
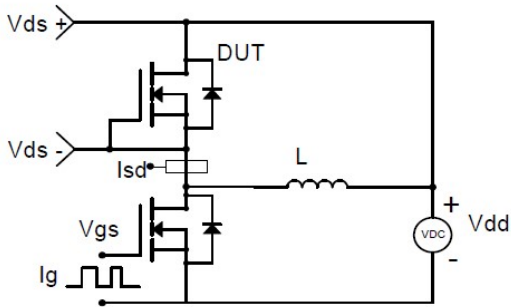


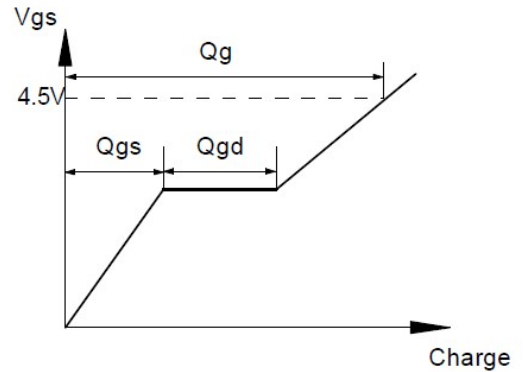
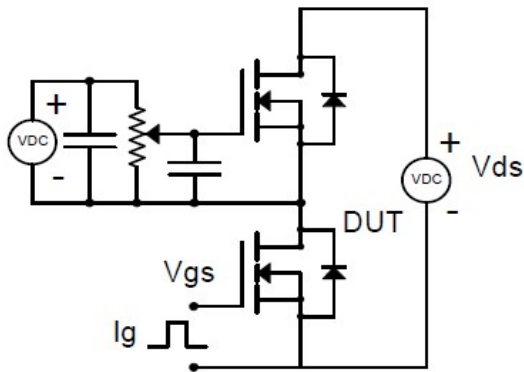
Figure9. Normalized Maximum Transient Thermal Impedance



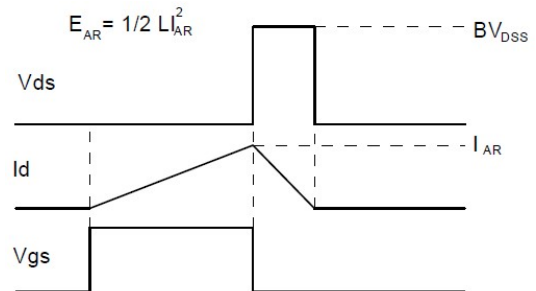
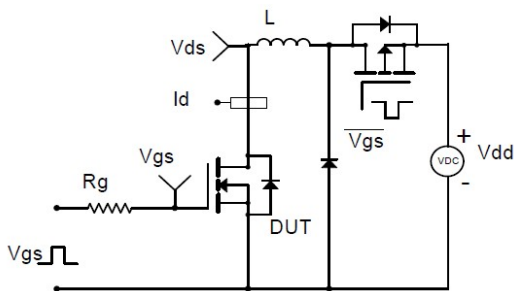
Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Gate Charge Test Circuit & Waveform

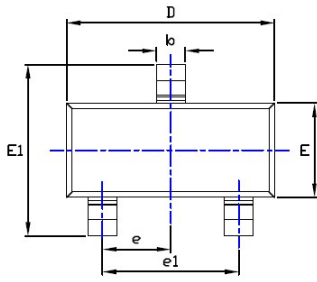


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

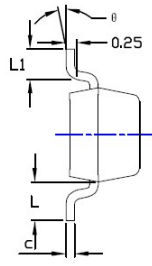


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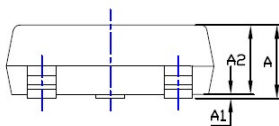
■ SOT-23 Package Information



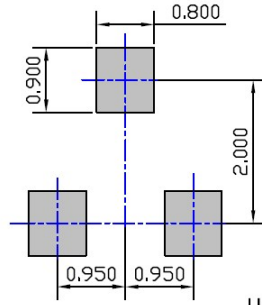
TOP VIEW



SIDE VIEW



SIDE VIEW



UNIT: mm

SUGGESTED SOLDER PAD LAYOUT

SYMBOL	DIMENSIONS					
	INCHES			Millimeter		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.035	---	0.045	0.900	---	1.150
A1	0.000	---	0.004	0.000	---	0.100
A2	0.035	0.038	0.041	0.900	0.975	1.050
b	0.012	0.016	0.020	0.300	0.400	0.500
c	0.004	---	0.008	0.100	---	0.200
D	0.110	0.114	0.118	2.800	2.900	3.000
E	0.047	0.051	0.055	1.200	1.300	1.400
E1	0.089	0.094	0.100	2.250	2.400	2.550
e	0.037TYP			0.950TYP		
e1	0.071	0.075	0.079	1.800	1.900	2.000
L	0.022REF			0.550REF		
L1	0.012	0.016	0.200	0.300	0.400	0.500
°	0°	---	8°	0°	---	8°

NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.



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